

Taiwanese IC Packaging & Testing Industry, 3Q 2021

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Abstracts

The report finds that shipment value of the Taiwanese IC packaging and testing industry, or OSAT (Outsourced Semiconductor Assembly and Testing) reached US\$5.4 billion in the second quarter of 2021 and registered over 9.4% sequential and 23.2% year-on-year growth. The Taiwanese industry's growth in the first half of 2020 performed better than the same period of 2019, mainly attributed to the order transfer of IDMs (Integrated Device Manufacturers) amid lockdowns worldwide. The overloaded capacity and the continued high demand for packaging and testing services are expected to lead to price rises. This is to contribute to the growth of the industry in the second half of 2021. Shipment value of the industry is anticipated to witness 10.5% sequential and 30.2% year-on-year growth in the third quarter of 2021 and throughout 2021.

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